Biristor Array Investigation

By Jeremiah Leit



A device that can be used for hardware based encryption and neural network computing

What is a Biristor?

- A biristor is a two terminal device with two different modes of operation.
 - 1) Silicon Controlled Rectifier Latch
 - 2) Neuron Fire mode
- It is essentially a floating base Bipolar Junction Transistor.
- The device can be either NPN or PNP however, in this project I am fabricating NPN devices.
- It observes an avalanche effect which changes the internal resistance of the device.
- This makes it essentially a type of resistor with volatile memory or memristor.

What do the I-V characteristics look like?



Silicon Controlled Rectifier Latch

mode of operation

J. Han and M. Meyyappan, "Trigger and Self-Latch Mechanisms of n-p-n Bistable Resistor," *IEEE Electron Device Letters*, vol. 35, no. 3, pp. 387–389, Mar. 2014.





Jin-Woo Han ; M. Meyyappan

Biristor applications?

- A latching change in the resistance value of the device which would allow it to be used as a memory element.
- The neural spiking method can be used to create neural networks that are designed to compute information more in manner more like a human brain than a microprocessor and possibly use less energy.
- If scaled properly the diode isolation from both directions as well as that caused by the dielectric TEOS around the device could create quantum dots.

What are my project goals?

- Fabrication of Biristors
- 1. Mask Design
- 2. Process Design
- 3. Fabrication
- 4. Electrical Testing
- Compare Measured Results to Published Results
- Determine Relation Between Scaling and I-V Characteristics

The Ion Implant Steps

- Replicate the device fabricated by Jin-Woo Han.
 Consulted for ion implantation details and other processes.
- 10^{21} • Three Implant steps (b) 10²⁰ Shallow arsenic implant Concentration (/cm³) 222nm $3x10^{15} \text{ cm}^{-3} 80 \text{keV}$ 10'° Boron implant 1018 8x10¹³ cm⁻³ 100keV 1017 Deep phosphorous implant 10¹⁶ 1x10¹⁴ cm⁻³ 500keV 200 600 800 400 Depth (nm) Implant done by Innovion

Mask Design For Individual Biristor



Biristor layout with probe pad



Biristor



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Mask Layout of Biristor Array



Pillar Dimensions range from 1.1um to 2.7um

Contact Dimensions are .5um

Main Array Area

Ion Implantation Profiles and Etching



Pillar Structure Formed After Etching





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Contact Cuts



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Final Device



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Completed Biristor Device

2.7umX2.7um Pillar



Biristor after the Metal Etch

SEM Micrographs of the Device

1.1um X 1.1um Device



Tool used JEOL JSM-IT100 LA

Courtesy of Bruce E. Kahn, AMPrint Center Rochester Institute of Technology

Measured I-V Characteristic



Conclusions

- During the process of fabricating the device several obstacles were overcome. Primarily the determination of how to etch the silicon pillars, how to get proper contact cut selectivity when using a dry etch tool and most importantly how to resolve .5um aluminum traces for wires. Additionally the mask design was difficult because design rules had to be determined. Proper probe spacing was achieved without the use of a template.
- Overall, these efforts resulted in a device that exhibited a biristor like I-V curve that displayed path dependent resistance. The reason for this discrepancy is yet to be determined.
- This was the first Biristor made at RIT.

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